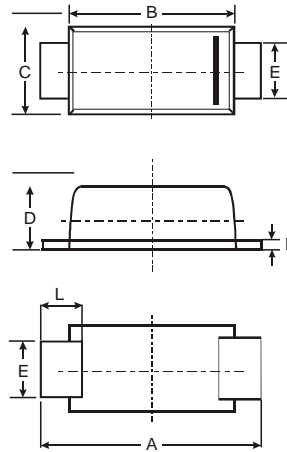


Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- High forward surge current capability
- High temperature soldering guaranteed:
250°C/10 seconds, 0.375(9.5mm) lead length,
5 lbs. (2.3kg) tension

Mechanical Data

- Case: JEDEC SOD-123FL molded plastic body over passivated junction
- Terminals : Plated axial leads,
solderable per MIL-STD-750, Method 2026
- Polarity : Color band denotes cathode end
- Mounting Position : Any
- Marking : M20
- Weight: 0.0007 ounce, 0.02 grams



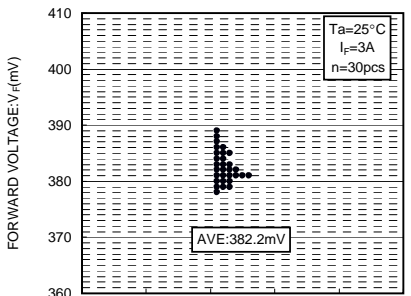
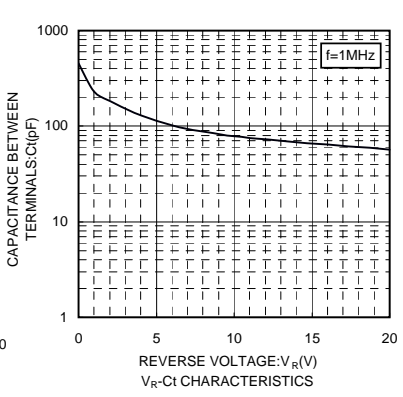
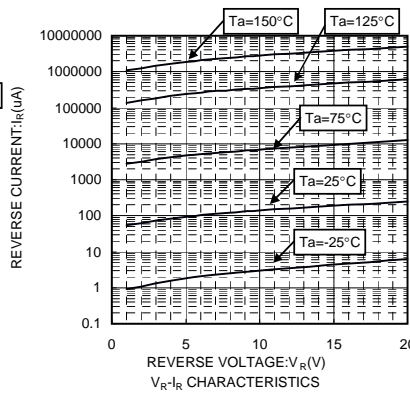
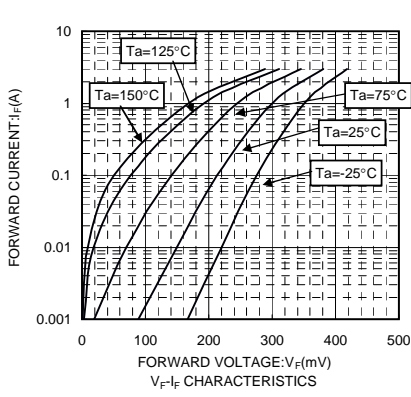
SOD-123FL			
Dim	Min	Max	Typ
A	3.50	3.80	3.65
B	2.60	2.90	2.75
C	1.70	1.90	1.80
D	0.09	1.10	1.00
E	0.08	1.10	0.095
H	0.12	0.20	0.16
L	0.07	0.09	0.08
All Dimensions in mm			

Maximum Ratings @ T_A = 25°C unless otherwise specified

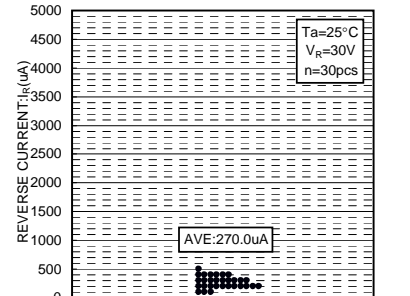
Parameter	Symbol	Limits	Unit
Reverse voltage (repetitive)	V _{RM}	20	V
Reverse voltage (DC)	V _R	20	V
Average rectified forward current Mounting on alumina board. T _c =95 °C Max.	I _o	3	A
Forward current surge peak (60Hz·1cyc)	I _{FSM}	30	A
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-40 to +125	°C

Electrical characteristics (T_a=25°C)

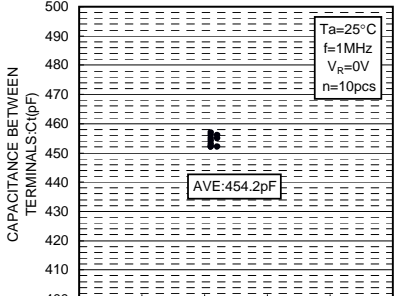
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V _F	-	-	0.46	V	I _F =3A
Reverse current	I _R	-	-	0.9	mA	V _R =20V



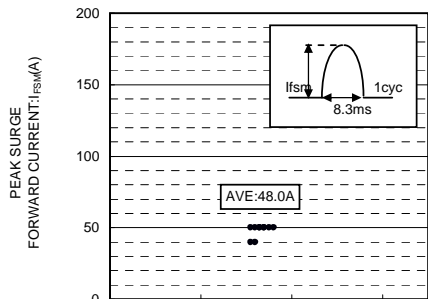
V_F DISPERSION MAP



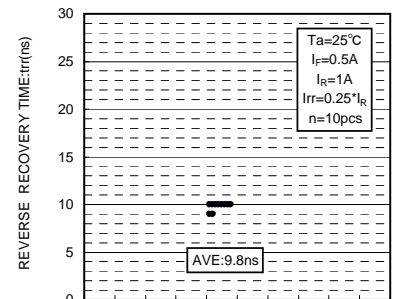
I_R DISPERSION MAP



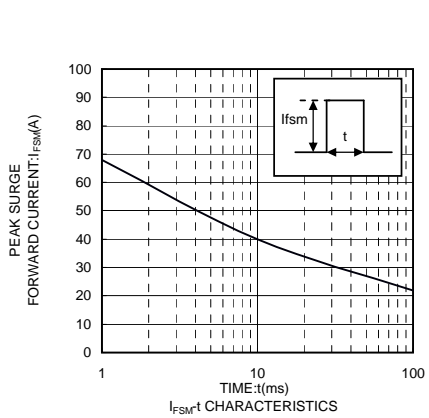
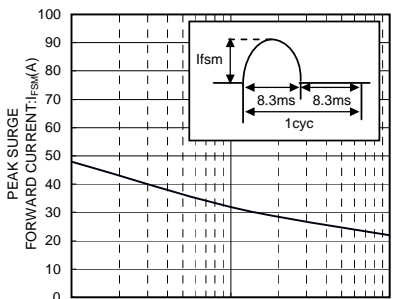
C_t DISPERSION MAP



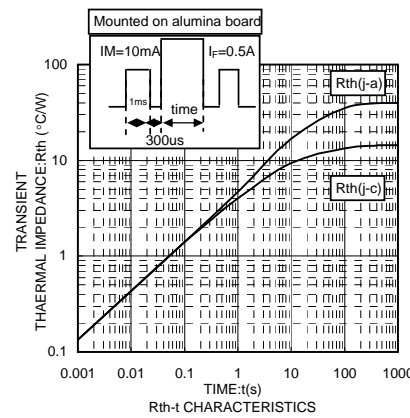
I_{FSM} DISPERSION MAP



t_{rr} DISPERSION MAP



I_{FSM} - t CHARACTERISTICS



R_{th} - t CHARACTERISTICS

